### NDDP010N25AZ

# Power MOSFET 250V, 10A, 420mΩ, N-Channel



www.onsemi.com

#### **Features**

- High Speed Switching
- Low Gate Charge
- ESD Diode-Protected Gate
- 100% Avalanche Tested
- Pb-Free, Halogen Free and RoHS Compliance

#### **Specifications**

Absolute Maximum Ratings at Ta = 25°C

Parameter	Symbol	Value	Unit
Drain to Source Voltage	VDSS	250	V
Gate to Source Voltage	VGSS	±30	<b>V</b>
Drain Current (DC)	ID	10	Α
Drain Current (Pulse) PW≤10μs, duty cycle≤1%	I <sub>DP</sub>	40	Α
Power Dissipation Tc=25°C	PD	1 52	W
Junction Temperature	Tj	150	°C
Storage Temperature	Tstg	– 55 to +150	°C
Source Current (Body Diode)	IS	10	Α
Avalanche Energy (Single Pulse) *1	EAS	15.5	mJ
Lead Temperature for Soldering Purposes. 3mm from Case for 10 Seconds	TL	260	°C

**Thermal Resistance Ratings** 

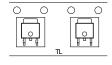
Parameter	Symbol	Value	Unit	
Junction to Case Steady State	$R_{\theta JC}$	2.40	°C/W	
Junction to Ambient *2	$R_{\theta JA}$	125		

Note:  $^{*1}$  VDD=50V, L=1mH, IAV=5A (Fig.1)

# 1. Gate 2. Drain 3. Source 4. Drain



#### Marking









Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### **Ordering & Package Information**

Device	Package	Shipping	Memo	
NDDP010N25AZT4H	DPAK(TP-FA), SC-63, TO-252	700pcs. / reel	Pb-Free	
NDDP010N25AZ-1H	NDDP010N25AZ-1H IPAK(TP), SC-64, TO-251		and Halogen Free	

<sup>\*2</sup> Insertion mounted

#### NDDP010N25AZ

#### **Electrical Characteristics** at Ta = 25°C

Parameter	Symbol	Conditions	Value			11-24
			min	typ	max	Unit
Drain to Source Breakdown Voltage	V(BR)DSS	I <sub>D</sub> =1mA, V <sub>GS</sub> =0V	250			V
Zero-Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =250V, V <sub>GS</sub> =0V			1	μΑ
Gate to Source Leakage Current	IGSS	V <sub>GS</sub> =±24V, V <sub>DS</sub> =0V			±10	μΑ
Gate Threshold Voltage	V <sub>GS</sub> (th)	V <sub>DS</sub> =10V, I <sub>D</sub> =1mA	2.5		4.5	٧
Forward Transconductance	9FS	V <sub>DS</sub> =10V, I <sub>D</sub> =5A		6.5		S
Static Drain to Source On-State Resistance	R <sub>DS</sub> (on)	I <sub>D</sub> =5A, V <sub>G</sub> S=10V		320	420	mΩ
Input Capacitance	Ciss			980		pF
Output Capacitance	Coss	V <sub>DS</sub> =20V, f=1MHz		80		pF
Reverse Transfer Capacitance	Crss			25		pF
Turn-ON Delay Time	t <sub>d</sub> (on)			18		ns
Rise Time	t <sub>r</sub>	0.5:0		26		ns
Turn-OFF Delay Time	t <sub>d</sub> (off)	See Fig.2		44		ns
Fall Time	tf			31		ns
Total Gate Charge	Qg			16		nC
Gate to Source Charge	Qgs	V <sub>DS</sub> =125V, V <sub>GS</sub> =10V, I <sub>D</sub> =10A		4.7		nC
Gate to Drain "Miller" Charge	Qgd			4.6		nC
Forward Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> =10A, V <sub>GS</sub> =0V		0.96	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	See Fig.3		130		ns
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>S</sub> =10A, V <sub>GS</sub> =0V, di/dt=100A/μs		540		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Fig.1 Unclamped Inductive Switching Test Circuit

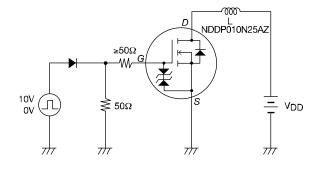


Fig.2 Switching Time Test Circuit

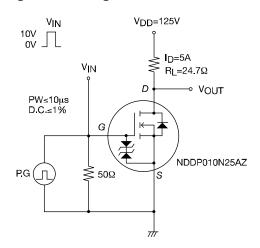
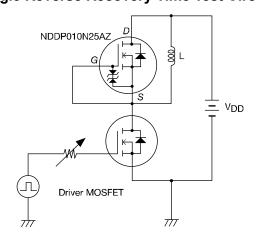
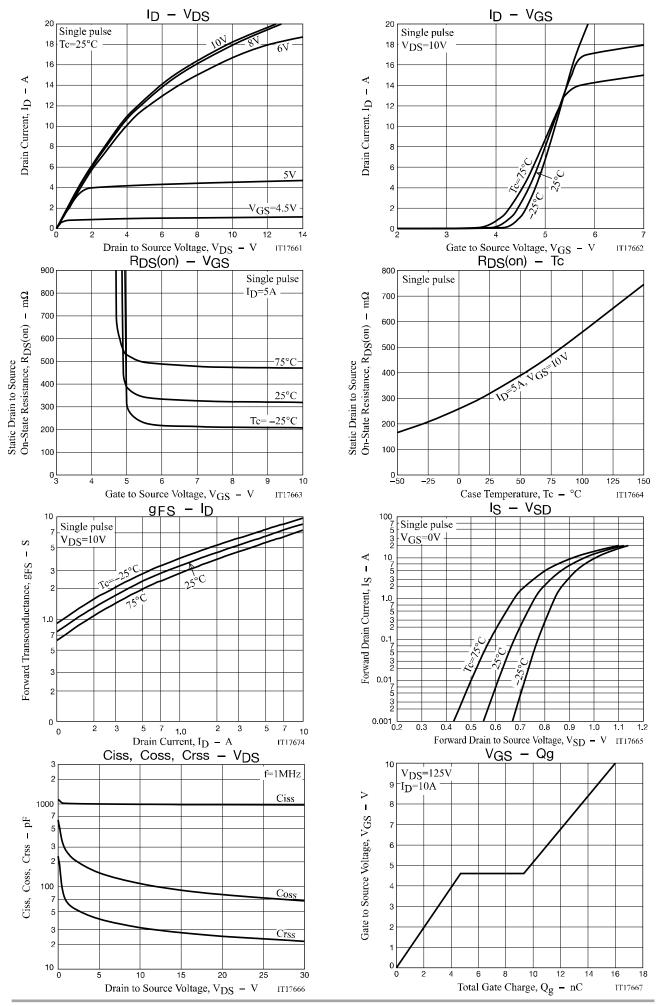
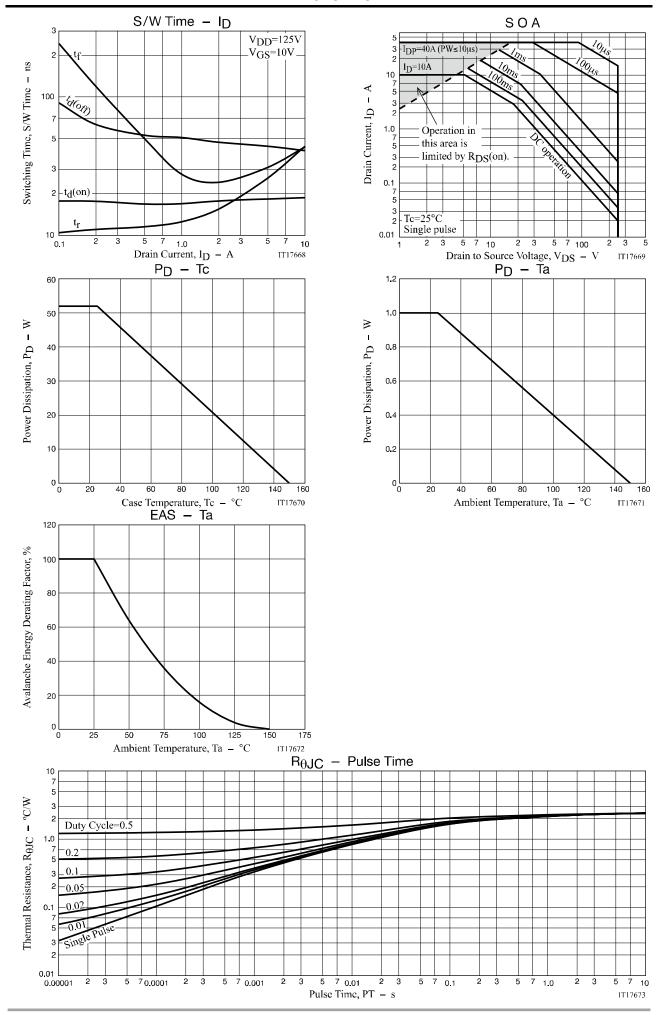


Fig.3 Reverse Recovery Time Test Circuit







#### **Package Dimensions**

NDDP010N25AZT4H

#### DPAK / TP-FA

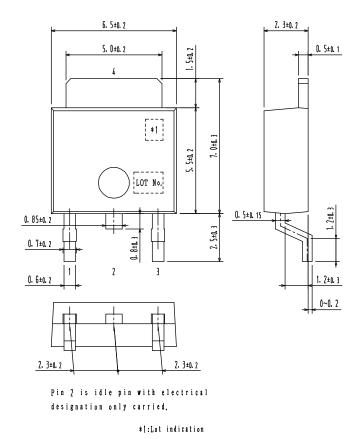
unit: mm



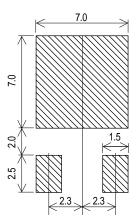
2:Drain

3:Source

4:Drain



## Recommended Soldering Footprint



#### **Package Dimensions**

NDDP010N25AZ-1H

#### **IPAK / TP**

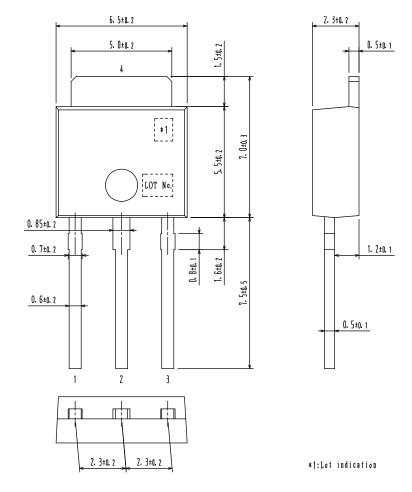
unit: mm

1:Gate

2:Drain

3:Source

4:Drain



Note on usage : Since the NDDP010N25AZ is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

ON Semiconductor and the ON logo are registered trademarks of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries. SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent re